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Kind regards,

Team Nexperia



# PMEG6045ETP

High-temperature 60 V, 4.5 A Schottky barrier rectifier

4 March 2013

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 4.5$  A
- Reverse voltage:  $V_R \leq 60$  V
- Low forward voltage
- High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- AEC-Q101 qualified
- High temperature  $T_j \leq 175$  °C

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption application

## 4. Quick reference data

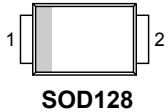

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 155$ °C; square wave	-	-	4.5	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	60	V
$V_F$	forward voltage	$I_F = 4.5$ A; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; $T_j = 25$ °C; pulsed	-	460	530	mV
$I_R$	reverse current	$T_j = 25$ °C; $V_R = 60$ V; pulsed	-	115	400	$\mu$ A



## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 <p>SOD128</p>	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6045ETP	SOD128	plastic surface-mounted package; 2 leads	SOD128

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6045ETP	DC

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
$I_F$	forward current	$T_{sp} = 150\text{ °C}$		-	6.3	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 35\text{ °C}$ ; square wave	[1]	-	4.5	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{sp} \leq 155\text{ °C}$ ; square wave		-	4.5	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; square wave		-	70	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	750	mW
			[3]	-	1250	mW
			[1]	-	2500	mW
$T_j$	junction temperature			-	175	°C



Symbol	Parameter	Conditions	Min	Max	Unit
T <sub>amb</sub>	ambient temperature		-55	175	°C
T <sub>stg</sub>	storage temperature		-65	175	°C

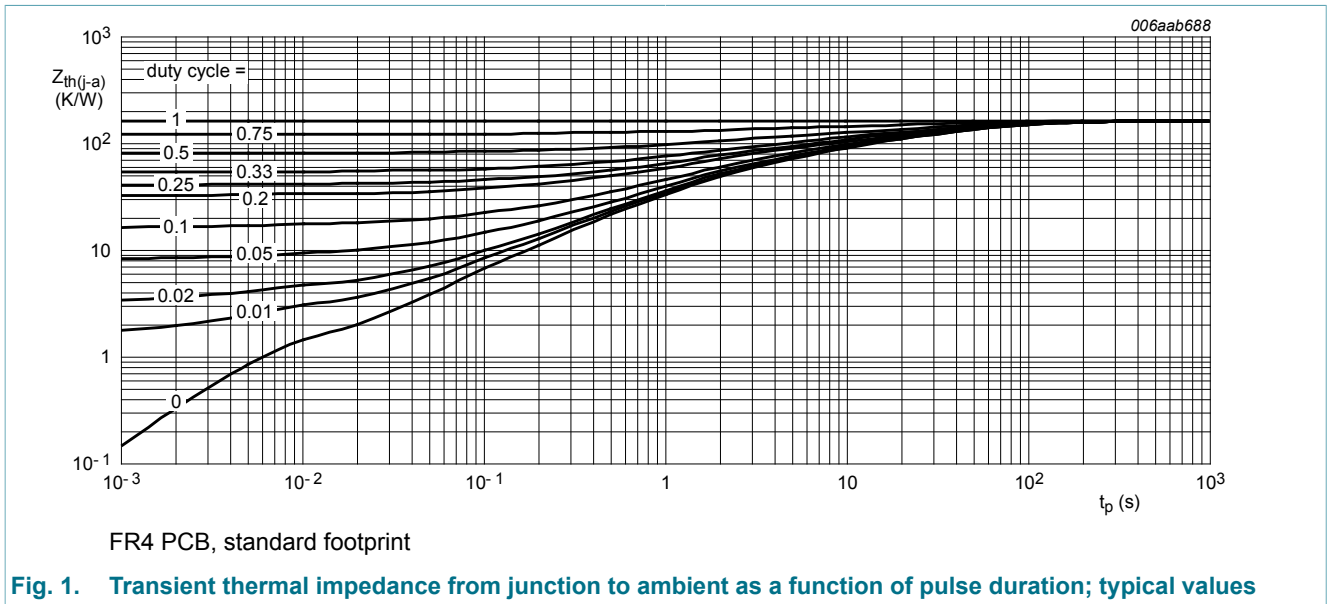
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1][2]	-	-	200	K/W
			[1][3]	-	-	120	K/W
			[1][4]	-	-	60	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[5]	-	-	12	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.



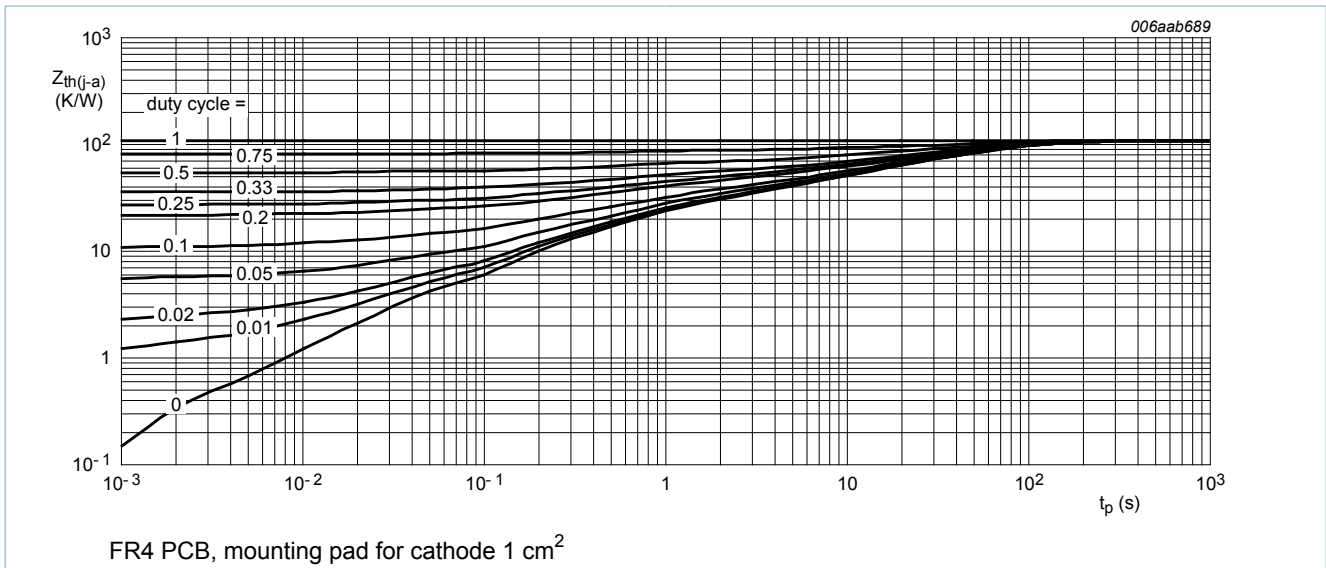


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

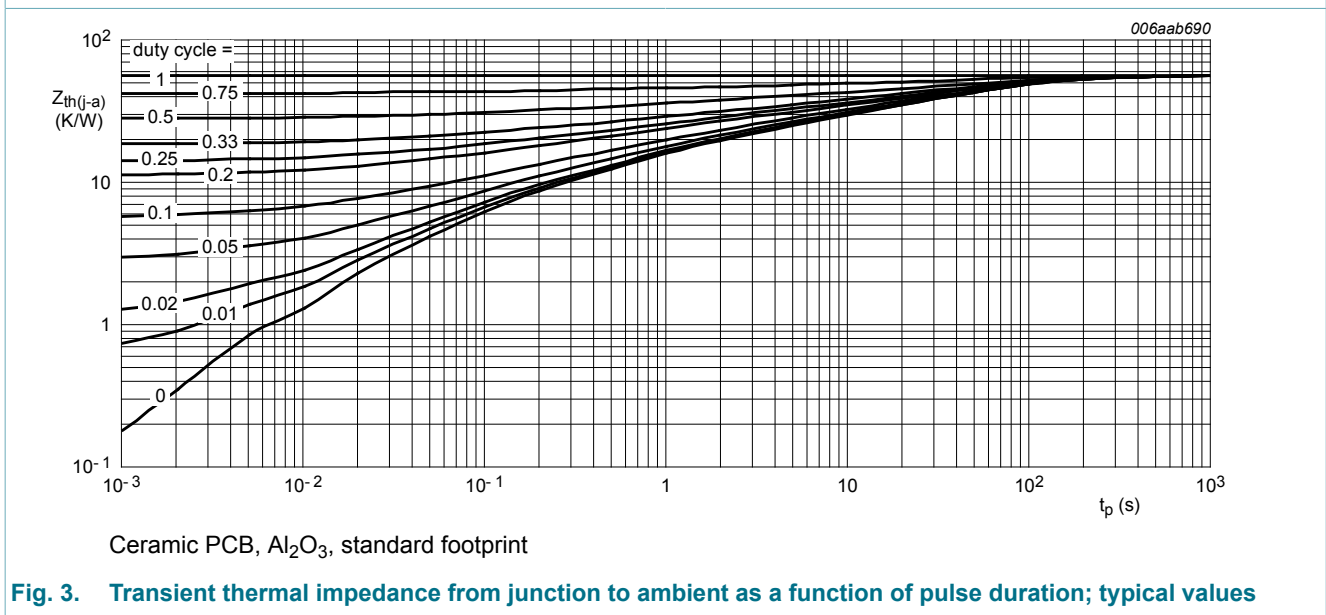


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

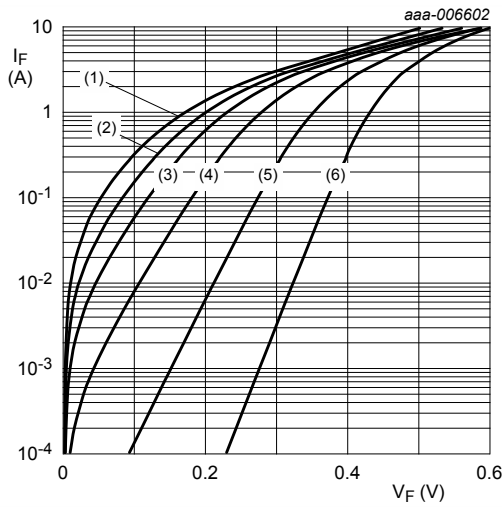
## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>j</sub> = 25 °C; pulsed	-	275	310	mV
		I <sub>F</sub> = 0.5 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>j</sub> = 25 °C; pulsed	-	325	-	mV
		I <sub>F</sub> = 1 A; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>j</sub> = 25 °C; pulsed	-	355	400	mV

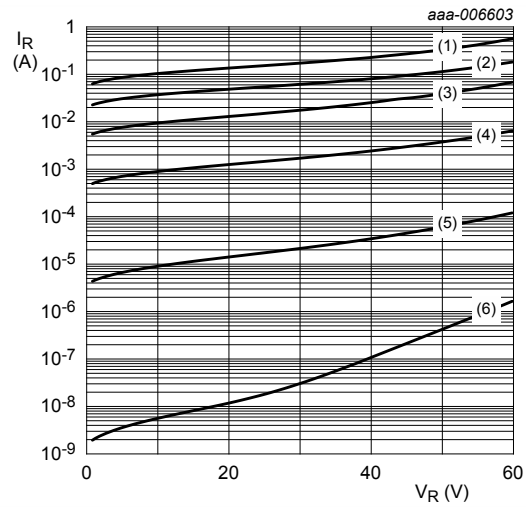
## High-temperature 60 V, 4.5 A Schottky barrier rectifier

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$I_F = 1.5 \text{ A}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	375	-	mV
		$I_F = 2 \text{ A}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	390	440	mV
		$I_F = 3 \text{ A}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	420	475	mV
		$I_F = 4 \text{ A}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	450	510	mV
		$I_F = 4.5 \text{ A}$ ; $t_p \leq 300 \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	460	530	mV
$I_R$	reverse current	$V_R = 5 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	7	20	$\mu\text{A}$
		$V_R = 10 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	9	40	$\mu\text{A}$
		$V_R = 30 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	20	80	$\mu\text{A}$
		$V_R = 60 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; pulsed	-	115	400	$\mu\text{A}$
		$V_R = 10 \text{ V}$ ; $T_j = 125 \text{ }^\circ\text{C}$ ; pulsed	-	9	-	mA
		$V_R = 60 \text{ V}$ ; $T_j = 125 \text{ }^\circ\text{C}$ ; pulsed	-	70	300	mA
$C_d$	diode capacitance	$V_R = 1 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	575	-	pF
		$V_R = 10 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	200	-	pF
$t_{rr}$	reverse recovery time	$I_F = 0.5 \text{ A}$ ; $I_R = 0.5 \text{ A}$ ; $I_{R(\text{meas})} = 0.1 \text{ A}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	20	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 1 \text{ A}$ ; $dI_F/dt = 40 \text{ A}/\mu\text{s}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	385	-	mV



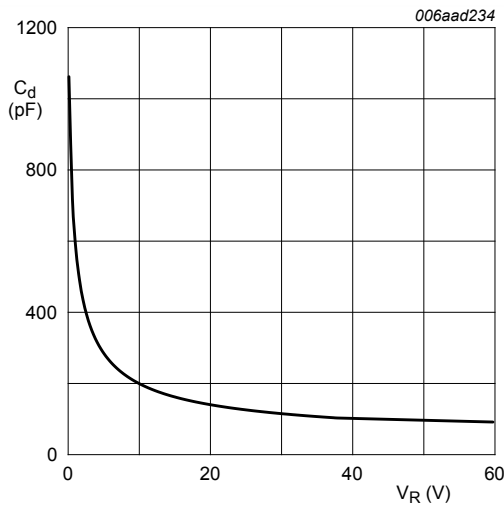
- (1)  $T_j = 175\text{ }^\circ\text{C}$
- (2)  $T_j = 150\text{ }^\circ\text{C}$
- (3)  $T_j = 125\text{ }^\circ\text{C}$
- (4)  $T_j = 85\text{ }^\circ\text{C}$
- (5)  $T_j = 25\text{ }^\circ\text{C}$
- (6)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 4. Forward current as a function of forward voltage; typical values**



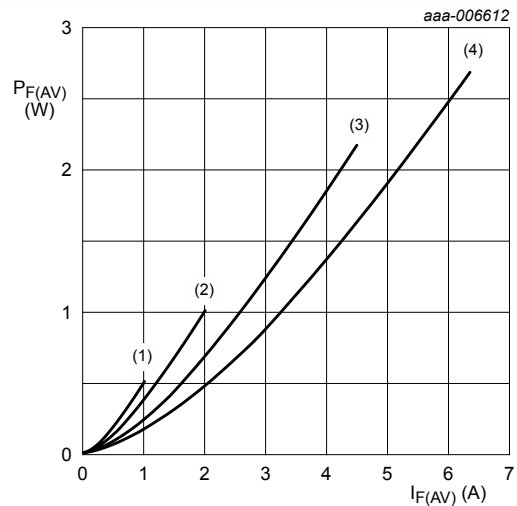
- (1)  $T_j = 175\text{ }^\circ\text{C}$
- (2)  $T_j = 150\text{ }^\circ\text{C}$
- (3)  $T_j = 125\text{ }^\circ\text{C}$
- (4)  $T_j = 85\text{ }^\circ\text{C}$
- (5)  $T_j = 25\text{ }^\circ\text{C}$
- (6)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 5. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

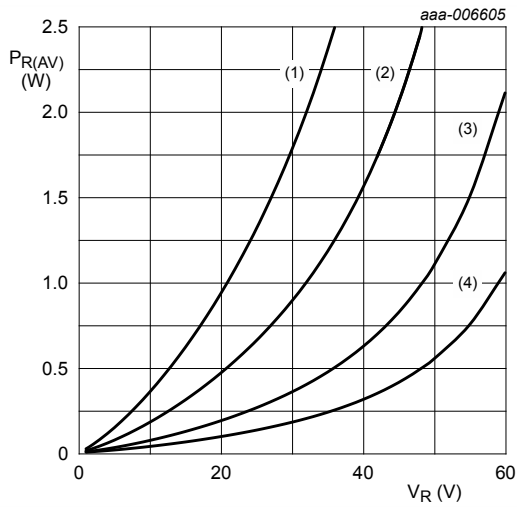
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



- $T_j = 175\text{ }^\circ\text{C}$
- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

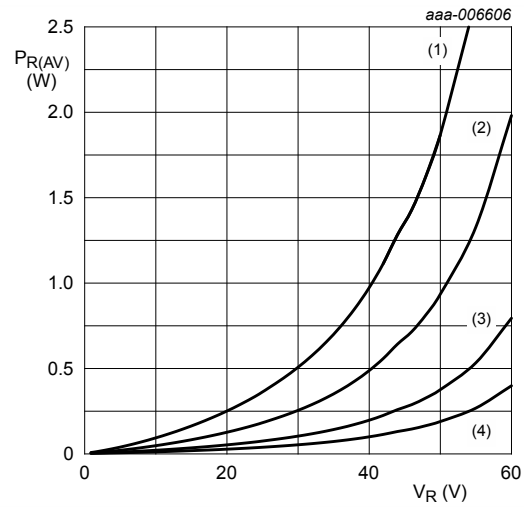
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**





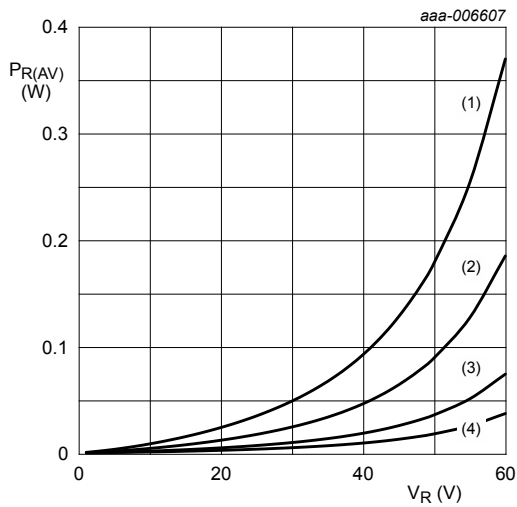
$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



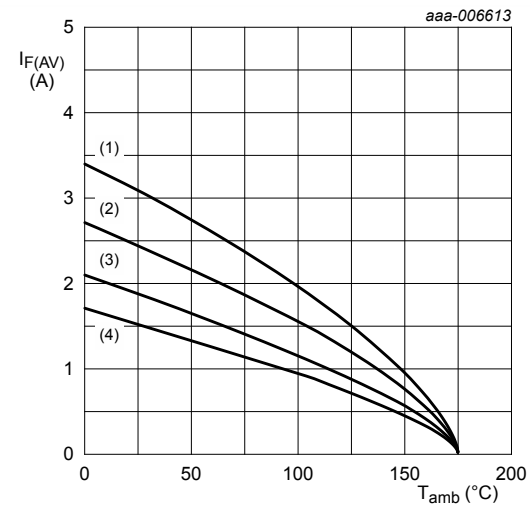
$T_j = 125\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



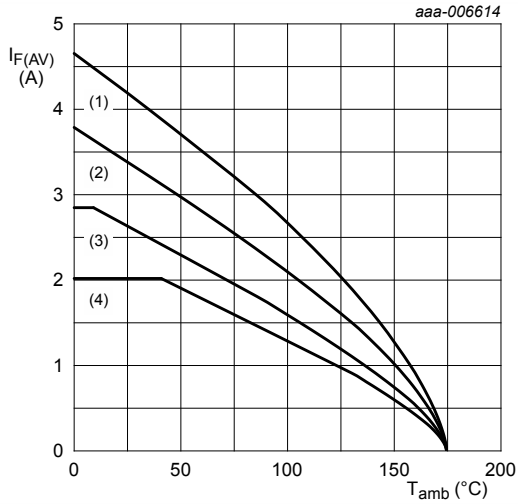
$T_j = 85\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values



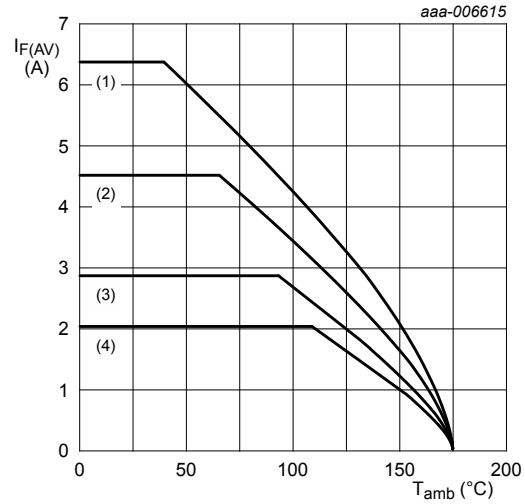
FR4 PCB, standard footprint  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$  (DC)  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



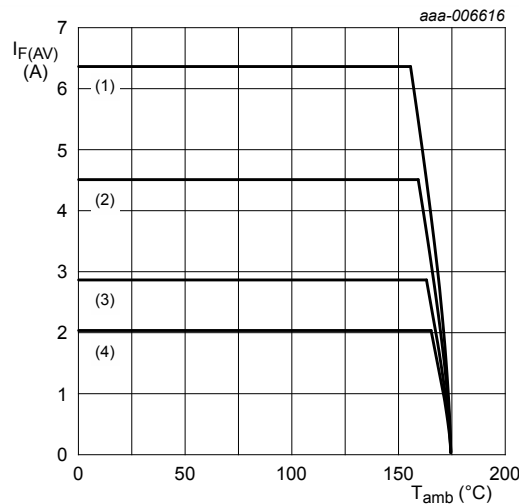
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 T<sub>j</sub> = 175 °C  
 (1) δ = 1 (DC)  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

**Fig. 12. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 T<sub>j</sub> = 175 °C  
 (1) δ = 1 (DC)  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

**Fig. 13. Average forward current as a function of ambient temperature; typical values**



T<sub>j</sub> = 175 °C  
 (1) δ = 1 (DC)  
 (2) δ = 0.5; f = 20 kHz  
 (3) δ = 0.2; f = 20 kHz  
 (4) δ = 0.1; f = 20 kHz

**Fig. 14. Average forward current as a function of solder point temperature; typical values**

### 11. Test information

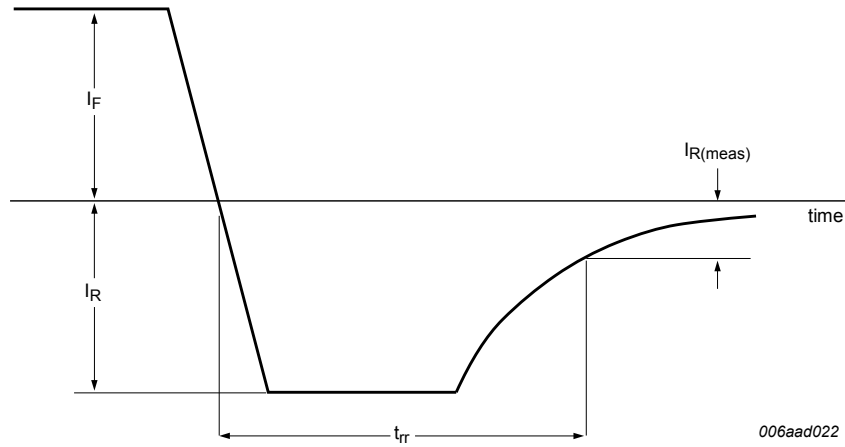


Fig. 15. Reverse recovery definition

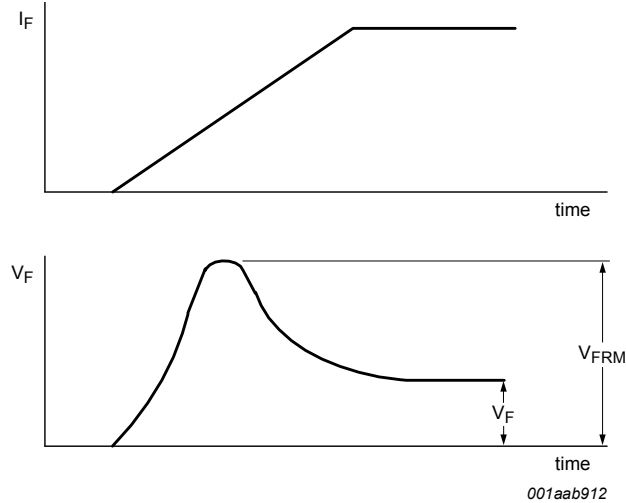


Fig. 16. Forward recovery definition

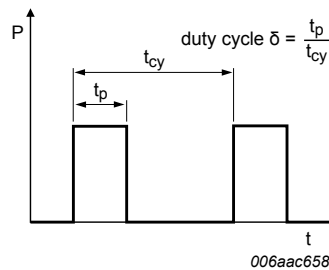


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  
 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline

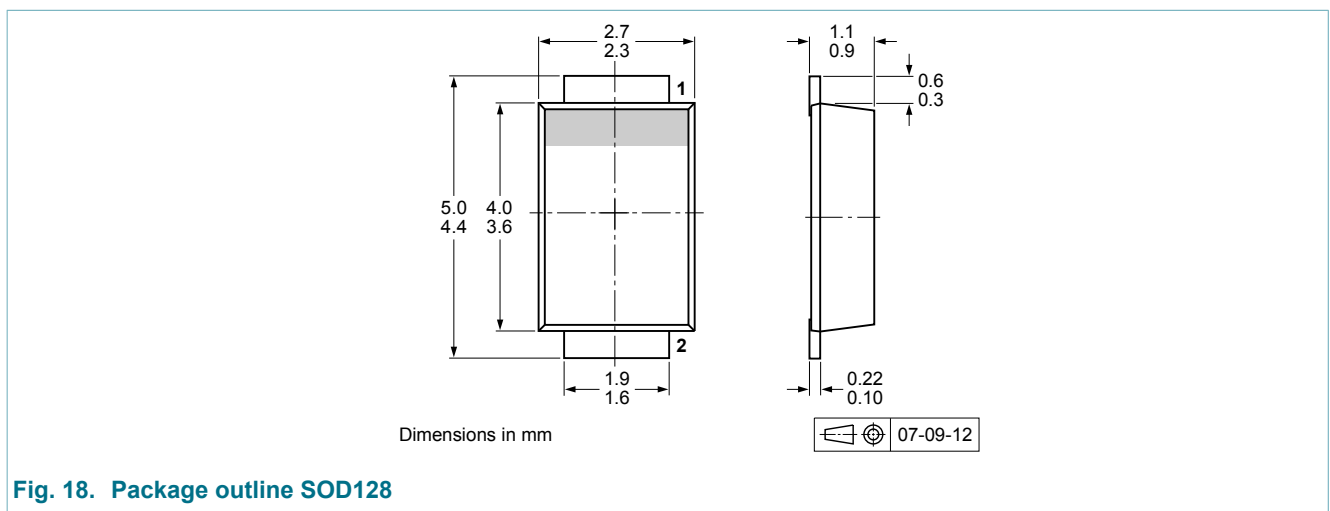


Fig. 18. Package outline SOD128

## 13. Soldering

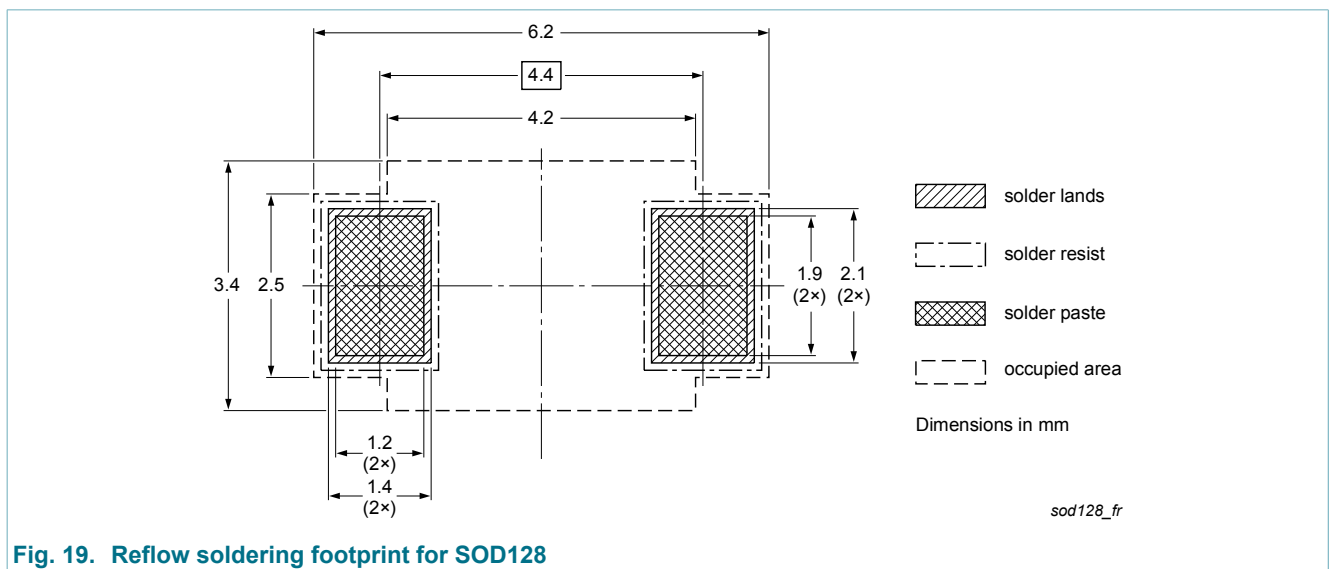


Fig. 19. Reflow soldering footprint for SOD128

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6045ETP v.1	20130304	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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